

Description

The SX3409MI uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

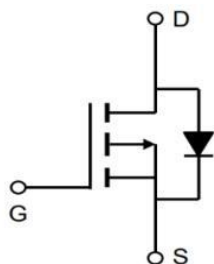
$V_{DS} = -30V$ $I_D = -12A$

$R_{DS(ON)} < 30m\Omega$ @ $V_{GS} = -10V$

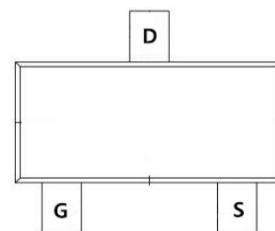
Application

Boost driver

Brushless motor



SOT-23-3L



Absolute Maximum Ratings ($T_c = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V^1$	-12	A
$I_D @ T_c = 70^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V^1$	-7.5	A
IDM	Pulsed Drain Current ²	-36	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation ³	1.8	W
TSTG	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	125	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	110	$^\circ C/W$

Electrical Characteristics (T_c=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30	-33	---	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-7A	---	25	32	mΩ
		V _{GS} =-4.5V , I _D =-5A	---	37	54	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.0	-1.5	-2.5	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =25°C	---	---	-1	uA
		V _{DS} =-24V , V _{GS} =0V , T _J =55°C	---	---	-5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =-5V , I _D =-7A	---	15	---	S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		15	30	Ω
Q _g	Total Gate Charge (-4.5V)	V _{DS} =-20V , V _{GS} =-4.5V , I _D =-7A	---	9.8	---	nC
Q _{gs}	Gate-Source Charge		---	2.2	---	
Q _{gd}	Gate-Drain Charge		---	3.4	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =-15V V _{GS} =-10V R _G =3.3Ω I _D =-5A	---	16.4	---	ns
T _r	Rise Time		---	20.2	---	
T _{d(off)}	Turn-Off Delay Time		---	55	---	
T _f	Fall Time		---	10	---	
C _{iss}	Input Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz	---	930	---	pF
C _{oss}	Output Capacitance		---	148	---	
C _{rss}	Reverse Transfer Capacitance		---	115	---	
I _s	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current	---	---	-8	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C	---	---	-1.2	V

Note :

- 1 、 The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2 、 The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3 、 The power dissipation is limited by 150°C junction temperature
- 4 、 The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

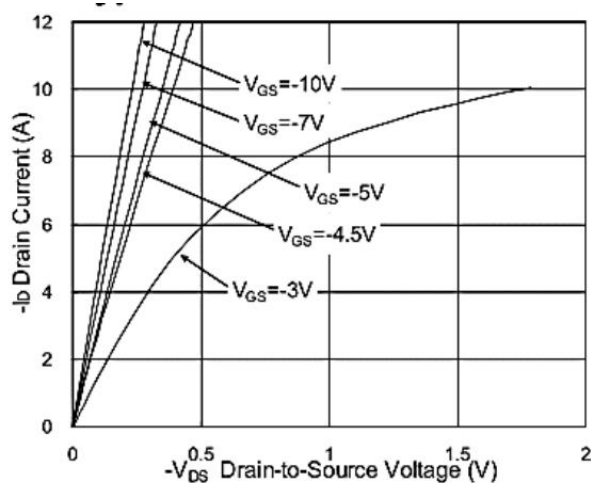


Fig.1 Typical Output Characteristics

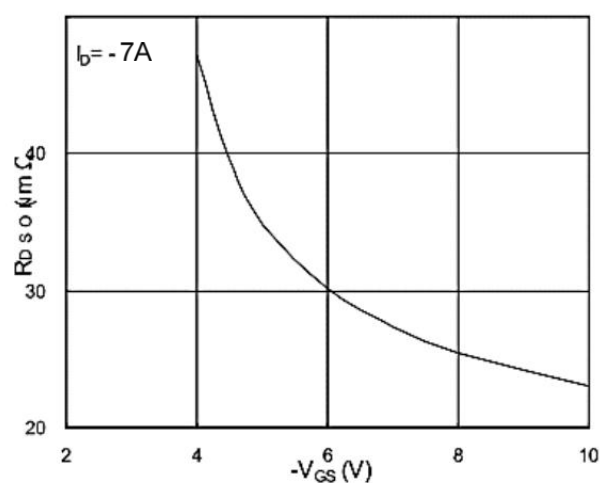


Fig.2 On-Resistance v.s Gate-Source

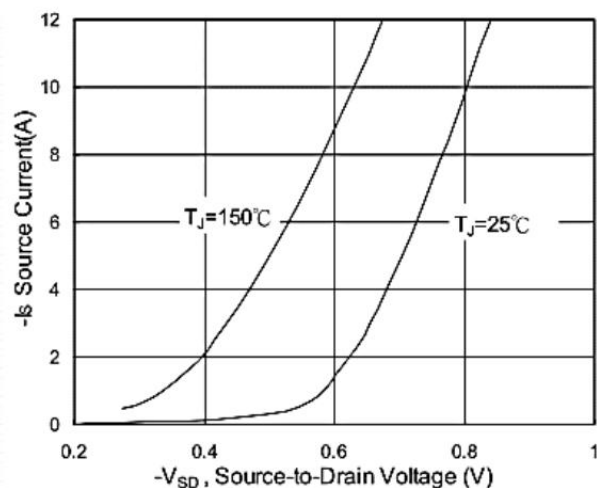


Fig.3 Forward Characteristics Of Reverse

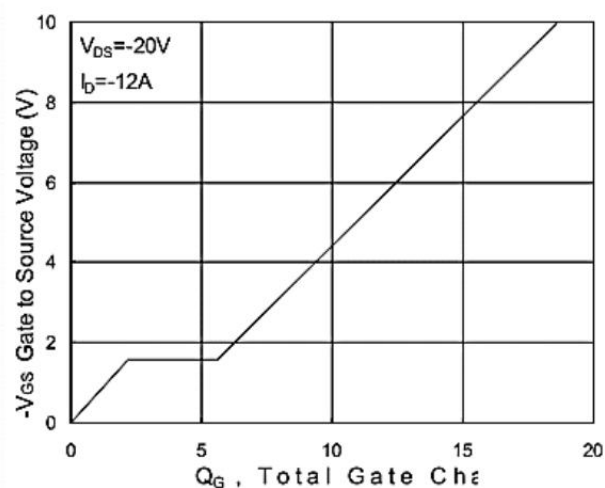


Fig.4 Gate-Charge Characteristics

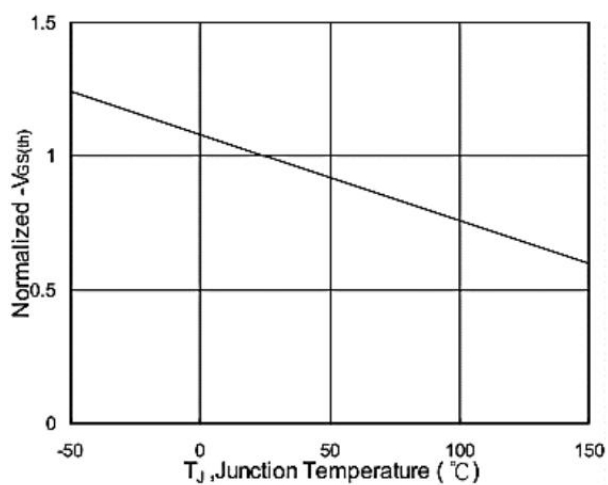


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

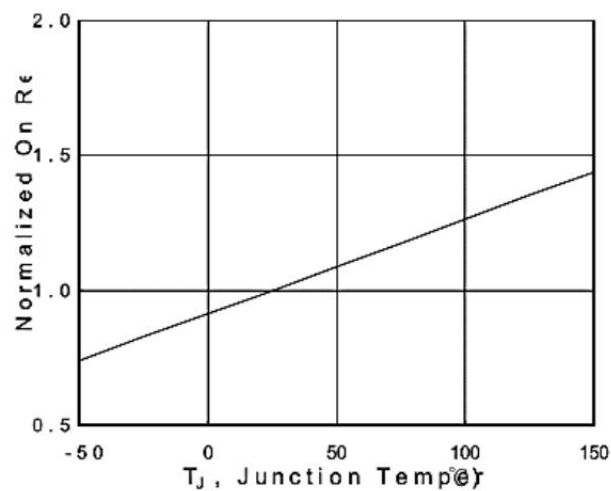


Fig.6 Normalized $R_{DS(on)}$ v.s T_J

Typical Characteristics

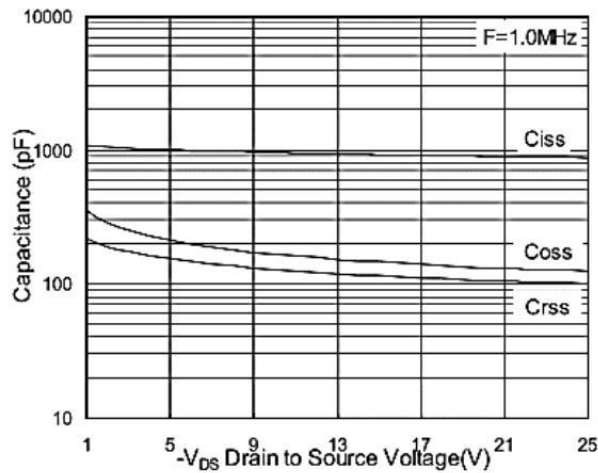


Fig.7 Capacitance

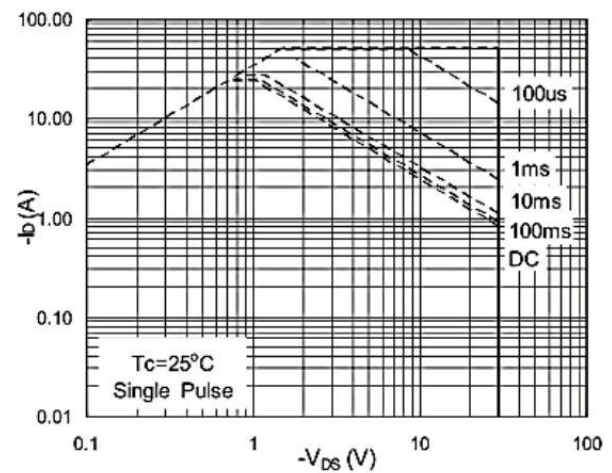


Fig.8 Safe Operating Area

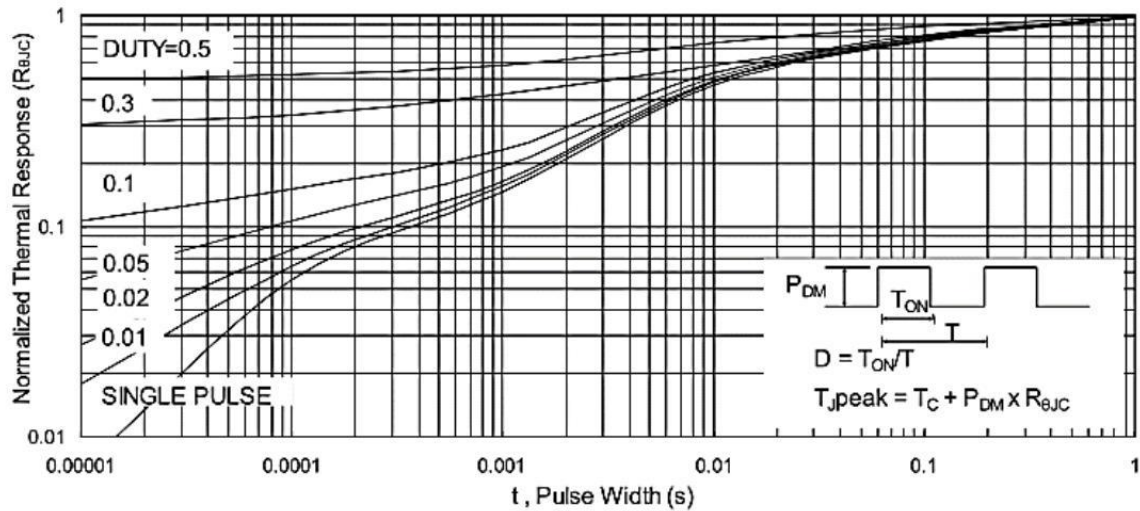


Fig.9 Normalized Maximum Transient Thermal Impedance

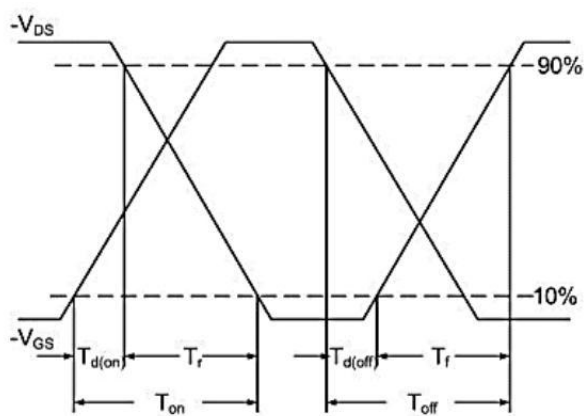


Fig.10 Switching Time Waveform

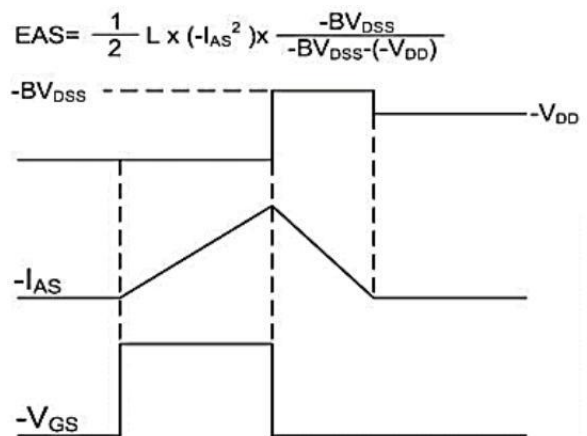
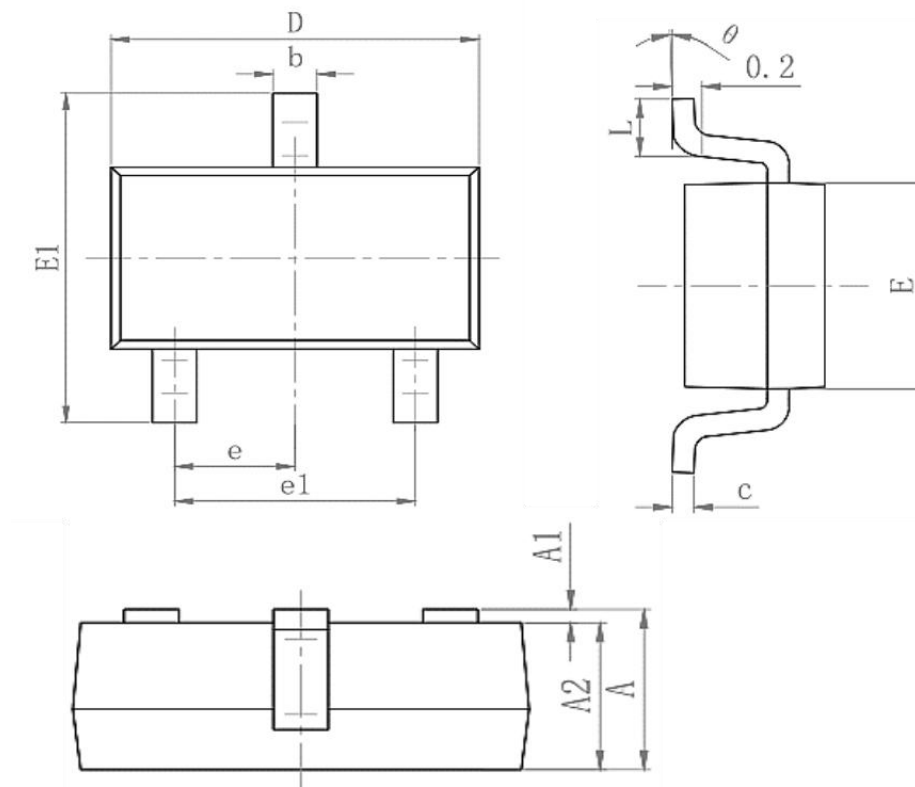


Fig.11 Unclamped Inductive Waveform

Package Mechanical Data-SOT23-3-XC-Single



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.25	0.45
c	0.100	0.200
D	2.820	3.020
E	1.5	1.7
E1	2.650	2.950
e	0.950(BSC)	
e1	1.800	2.000
L	0.300	0.500
θ	0°	8°

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	SOT23-3L		3000